## Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of the claims in the application:

## Listing of Claims:

1. (currently amended) A method comprising:

determining a concentration of a conductive metal for a low-acid electroplating solution; and

determining a concentration of a leveler for the low-acid electroplating solution based upon the concentration of the conductive metal such that the leveler concentration is sufficient to reduce a within die thickness variation to a specification value,

wherein the concentration of the leveler is at least about 12ml/l.

2. (currently amended) The method of claim 1 wherein the conductive metal is copper and the concentration of the leveler is ~~within the range 4ml/1-12ml/l of leveler~~ between about 15ml/l and about 20ml/l within the low-acid electroplating solution.

3. (original) The method of claim 2 further comprising:

determining a concentration of suppressor for the low-acid electroplating solution based upon the concentration of leveler such that the concentration of suppressor is sufficient to substantially reduce a plurality of electroplating defects.

4. (original) The method of claim 3 wherein a combined concentration of leveler and suppressor is determined to be below a specified value.

5. (previously presented) The method of claim 3 wherein the concentration of suppressor is within the range 1 ml/1-6 ml/1 of suppressor within the low-acid electroplating solution.

6. (original) The method of claim 3 further comprising:

determining a concentration of a chloride for the low-acid electroplating solution such that the chloride concentration is sufficient to catalyze the suppressor.

7. (original) The method of claim 5 further comprising:

determining a concentration of an accelerator for the low-acid electroplating solution based upon the leveler concentration and the suppressor concentration.

8. (previously presented) The method of claim 5 wherein the accelerator concentration is in the range of 1 ml/1-3.3 ml/1 of accelerator within the low-acid electroplating solution.

9-24. (canceled)